

Windows 7 Ultimate 32-bit Original Key 94fbr [NEW]

I hope you will find right Windows 7 ultimate serial keys for your. Windows 7 Ultimate 64 Bit Keys: Use these Windows 7 Ultimate Serial Keys to make your OS genuine. FRRRW-WEQAW-SEDRF-TGUHI-JBIUV 56GTF-CVBXX-. Free Windows 7 Product Key Generator,PC activator from www.windowupdates.net,Genuine Product Key for Windows 7 Professional. The most common problem today we have seen is customer sending us the Windows 7 activation key after unlocking. .1. Field of the Invention The present invention relates to a semiconductor device and a method of manufacturing the same. 2. Description of the Related Art Recent semiconductor devices have been multilayered by stacking a plurality of multilayered circuit chips. In this case, the multilayered circuit chips are electrically connected together by a vertical connection structure such as through-hole connection or via-hole connection. The via-hole connection is generally formed through a metal interconnection formed in each chip. The metal interconnection formed in each chip is electrically connected to a metal interconnection (wiring) connected to a bonding pad of a chip on the other chip side via the via-hole connection. When the through-hole connection is applied to a semiconductor device, a through-hole is formed in a chip before the chip is mounted on a substrate. The through-hole formed in the chip is aligned with a through-hole formed on the substrate to be connected. A bump is formed on the surface of the chip, and the bump is bonded to a pad formed on the surface of the substrate to be connected by reflow. A process of bonding the bump to the pad on the substrate side is referred to as a thermo-compressive bonding (TCB) process. The thermo-compressive bonding process requires heating for pressing the bump on the chip surface side against a substrate to be connected and allows a gap to occur between the chip and the substrate to be connected. A process of filling the gap with an underfilling material is also required. U.S. Pat. No. 6,147,309 discloses a semiconductor device having a multilayered interconnection structure (semiconductor multilayered board) in which a multilayered interconnection formed in each chip is electrically connected to an interconnection on a substrate side. According to this multilay

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